

Quarterly Reliability Monitoring Results

Quarters: Q1/2023 to Q4/2024

Based on structural similarity

| Supplier               |  | User Part Number  |                                   |           |            |           |
|------------------------|--|---|-----------------------------------|-----------|------------|-----------|
| Nexperia B.V.          |  | PUSB3AB6  |                                   |           |            |           |
| Name of Laboratory     |  | Part Description  |                                   |           |            |           |
| Nexperia ATGD          |  | NXP ICN8<br>MCD package, Subcon UTAC<br>Protection INDI   |                                   |           |            |           |
| Based on AEC-Q101 Test |  | Test Conditions   | Duration                          | # Lots    | # Quantity | # Rejects |
| # 1                    | <b>TEST</b><br>Pre- and Post-Stress<br>Electrical Test         | Tamb = 25 °C  | N/A                               | see below | all parts  | see below |
| # 2                    | <b>PC</b><br>Preconditioning                                   | JESD22-A113<br>Bake Tamb = 125 °C<br>Soak Tamb = 85 °C, RH = 85%<br>Reflow soldering              | 24 hours<br>168 hours<br>3 cycles | 72        | 2880       | 0         |
| # 5                    | <b>HTRB</b><br>High Temperature Reverse<br>Bias                | MIL-STD-750-1<br>M1038 Method A<br>Tj = Tjmax, Vr = 100% of max. datasheet<br>reverse voltage     | 1000 hours                        | 38        | 1520       | 0         |
| # 7                    | <b>TC</b><br>Temperature Cycling                               | JESD22-A104<br>-65 °C to Tjmax, not to exceed 150°C   | 1000 cycles                       | 24        | 960        | 0         |
| # 8 or                 | <b>UHAST</b><br>Unbiased HAST                                  | JESD22-A118<br>Tamb = 130 °C, RH = 85 %   | 96 hours                          | 24        | 960        | 0         |
| # 8a                   | <b>AC</b><br>Autoclave   | JESD22-A102<br>Tamb = 121 °C, RH = 100 %<br>Pressure = 205 kPa (29.7 psia)                        |                                   |           |            |           |
| # 9                    | <b>H3TRB</b><br>High Humidity High<br>Temperature Reverse Bias | JESD22-A101<br>Tamb = 85 °C, RH = 85%, VR = 80 % of<br>rated reverse voltage <sup>[1]</sup>       | 1000 hours                        | 24        | 960        | 0         |
| # 10                   | <b>IOL</b><br>Intermittent Operating Life                      | MIL-STD-750 Method 1037<br>ton = toff, devices powered to insure ΔTj =<br>100 °C for 15000 cycles | 1000 hours                        | n.a.      | n.a.       | n.a.      |
| # 20                   | <b>RSH</b><br>Resistance to Solder Heat                        | JESD22-A111<br>260 °C ± 5 °C  | 10 s                              | n.a.      | n.a.       | 0         |
| # 21                   | <b>SD</b><br>Solderability                                     | J-STD-002   |                                   | 22        | 660        | 0         |

[1] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1)  
Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

| Wafer Fab | Technology      | Quantity | Rejects | Failure Rate (FIT) | MTTF (hrs) |
|-----------|-----------------|----------|---------|--------------------|------------|
| NXP ICN8  | Protection INDI | 1520     | 0       | 2,79               | 3,58E+08   |